

Transaction Information

Tool ID	STP2352
Tool Status	Connected
Location	Malta, USA
Wafer Size	300 mm
Fab Section	Lithography
Tool Available Date	2024-10-29

General Product Information

Vendor Supplier	ASML
Model	NXT1950i
Vintage	2012
Serial No	m5190
Asset Description	ASML NXT1950i immersion scanner
Software Version	6.1
CIM	SECS, GEM
Process	Litho

Hardware Configuration (Fab)

System Type	Description	Quantity	Status
Handler System	N/A		OK
Factory Interface	SMIF	2	OK
Others			
Main System	Scanner	1	OK
Options System			

Hardware Configuration (Subfab / Auxilliary Units)

Description	Quantity	Status
Entegris Liquid Lens	1	OK
ACC Donaldson filter cabinet	1	OK
Power VAR	1	OK

Missing/Faulty Parts / Accesories List

Description	Quantity
NONE	

Tool Pictures

General

Fab tool





Hardware Sub-fab

NONE



Hardware Sub-fab

NONE



Hardware Sub-fab

NONE



Hardware Sub-fab

NONE



Hardware Sub-fab

NONE



Hardware Sub-fab

NONE



Manufacture Serial

NONE

101121
Mat: 4022.635.53201
S/N: 62068
BID: 000000000105980486
 **ASML**
A B C D E

MAT: 4022.635.53231
S/N: 000000000106101980
BID: 000000000106101980
 **ASML**
B C D E

 **ASML**  DE RUN 6501
5504 DR VELDHOVEN
THE NETHERLANDS

MACHINE TYPE	: NXT:1950i
12NC	: 9428.999.65720
SERIAL NO.	: 5190
VOLTAGE/TYPE	: 230/400VAC / 3PH+N+PE
FREQUENCY	: 50/60 HZ

Additional Tool Data Files

Parameter	STP2352
(DUV) Reticle Handler Robot Barcode Reading Position	Original robot position to read reticle barcode
(DUV) Reticle Handler Robot Damper Hardware Configuration.	Robot does not include a mass damper.
2D Barcode Reader	Present
2D Barcode Reader at Load Port	2D Barcode Reader option is disabled
4par COWA allowed leveling strategies	4par COWA with LDL and LIL leveling strategy is allowed
A Focus Calibration Method using CDM or CDM3 model	A Focus Calibration Method with the CDM model
AA processing rack	MMCR processing rack
ALE 1 Use	NA
APACE used in production.	APACE is disabled in production.
APAXLE mode of operation	APAXLE is not controlled
Ability to use remote test service	Remote test service is enabled
Activate ESO MAX speed Allowed. Protected	ESO MAX Speed Allowed Disabled
Activation of the airknife during hovering	Not applicable
Active Pupil Aberration Correction Element type	APACE type 1
Active Pupil Aberration Correction lens Element	Metrology uses one APACE with optics B
Active Set DLM, various improvements and Image Tuner fix	DLMv2.0
Active wafer release for dry WS	
Actuation mode for SBC Overlay corrections	DEFAULT
Agile NXE matching algorithms for NXE systems	Disabled
Air Gauge	Present
Air Gauge Improved Levelling	AGILE2
Airmounts hardware type	MK 4.2 with airtank
Alignment Camera Mirror	NA
Alignment Recipe Override	Alignment Recipe Override Disabled
Alignment Sensor Type	Smash OM
Alignment Strategy ID Standard or Extended. Protected.	Alignment Strategy ID max length is 15 characters
Alignment White light Source Wavelength Configuration	None
Alignment laser configuration	4 color laser
Alignment marks segment used during HSA on PARIS	NA
Alignment overlay and TPT node	Alignment Overlay and TPT Performance node 19
Allow L1L7 Type 1 Optimization	Absent
Allow different Exp,TIS Align set	Present
Allow even orders usage	Present
Allow wafer plane deviation check with Focus Monitoring	Disabled
Allowed wafer load grid improvement level	Until Level 1
Alternate RH robot firmware selection	Disabled
Angular sensitivity corrections of ESCAL sensor	Disabled

on Chuck 1	
Angular sensitivity corrections of ESCAL sensor on Chuck 2	Disabled
Angular sensitivity corrections of Spot Sensor on Chuck 1	Enabled
Angular sensitivity corrections of Spot Sensor on Chuck 2	Enabled
Application Specific Lens Heating Calibration & Verification	Present
Application Type	Scanner Application
Apply RBF Relaxation	Disable RBF Relaxation
Apply clamping grid correction during wafer align	disabled;
Apply grid corrections on unidirectional marks	Use zero to correct unmeasured directions
Assure System Snapshots	Assure System Snapshots not allowed
Asynchronous flexwave control during exposure	NA
Athena Focus Improvements 1	Present
Athena Narrow Marks Twinscan	Present
Attenuator Mirror Type	Quartz Attenuator Mirror
Attenuator Type	Variable
Automated DOE Exchanger	Absent
Automated DOE Exchanger Architecture	16 slots
Automated Lens Heating Calibration	Enabled
Automated Reticle Transport System	Light Curtain
Automatic CUA	Absent
Automatic CUA exchanger architecture	Adjacent to the Rema objective
Automatic PCE exchanger	Present
Availability of chucks in the waferstage compartment.	Both chucks are present.
Availability of inline grid-jump detection @ expose.	Grid Jump Detection at Expose functionality not available.
Availability of the FlexWave module	FlexWave module not available
Avoid I1 or I2 mark on TIS plates	Enabled;
Avoid Track INPUT/OUTPUT conflicts, Raise AS after APR	Avoid Track INPUT/OUTPUT conflicts enabled
BALE Type	Piezo Valves
BES switching behavior	Controlled by CEX
BMU Hardware version	Version 2
Backup method for machine data	Legacy, using asml_backup_settings
Barcode Reader at Load Port	There is no barcode reader at the load port
Barcode Reader configuration at IRL.	Omron 2D camera present at IRL.
Barcode Reader near the internal reticle library	Barcode reader is HAWKEYE type
BaseLiner Optima WEC/REC Control	BaseLiner Optima WEC/REC application is enabled.
BaseLiner focus control.	BaseLiner-Focus application is enabled.
BaseLiner focus high order intrafield	BaseLiner-Focus high order intrafield is disabled.
BaseLiner overlay control.	BaseLiner-Overlay application is enabled.
BaseLiner overlay high order intrafield	BaseLiner-Overlay high order intrafield is enabled.

Baseframe accelerometer box	Absent
Baseliner Astigmatism based focus stability control.	Disabled
Baseliner MMO focus stability control	Baseliner MMO focus stability control is disabled
Baseliner MMO overlay stability control	Baseliner MMO overlay stability control is disabled
Baseliner diffraction based focus stability contro	Baseliner diffraction based focus stability control enabled
Beam Control	Closed loop
Behavior of the FlexWave module	FlexWave not controllable
Bubble Extraction Seal Setting	NA
CD-FEC/FWOL spots selection corrections	Sub-optimal in corner cases
CDC	Enabled
CDU Optimizer generic dose corrections	Disable generic CDU Optimizer
CEX park decision version	Use park decision version 0
COWA with a 6-parameter model	Disabled
CTC type per recipe layer definition.	Disabled
Carrier Handler Type	Mark III 300
Choice of avoidance routing.	Phase 5
Choice of horizontal stage align setpoint	Reuse previous vertical stage align result
Chuck 1 wafer size	300mm
Chuck 2 wafer size	300mm
Chuck Dedication	Enhanced
Chuck specific calibration of field curvature.	Disabled
Circuit Dependent - Focus Edge Clearance application mode	Mode1: CDFEC is ON when yield. AND non-yield. dies present
Circuit Dependent FEC	Present
Clean Air Configuration	NA
Clean Air Temperature Control	NA
Clean Air Temperature Performance level	NA
Combined stage alignment	Enabled
Communication with Air Control Cabinet	RS232 communication
Computational ASCAL	Commercial cASCAL option enabled
Concatenation of actions prior to exposure	NA
Conditionally reset the POB	Include POB in system reset
Configuration Identification CARM Stages Stack	Version 0
Configuration identification CARM Handlers Stack	No Configuration Specified
Configuration identification for AMCR electronics	Config 1
Configuration identification for GPAB electronics	No configuration specified
Configuration identification for GPAS electronics	No configuration specified
Configuration identification for SACR electronics	No configuration specified
Configuration identification for WH part of the SACR Rack	No configuration specified
Configuration identification for immersion electronics	Config 2
Configuration identification reticle positioning electronics	Config 3

Configuration identification wafer positioning electronics	Config 10
Configuration identifier planar stage chuck 1 linear axis	Version 2
Configuration identifier planar stage chuck 1 long stroke	Version 2
Configuration identifier planar stage chuck 1 short stroke	Version 5
Configuration identifier planar stage chuck 2 linear axis	Version 2
Configuration identifier planar stage chuck 2 long stroke	Version 2
Configuration identifier planar stage chuck 2 short stroke	Version 5
Configuration of planar stage chuck 1 corner-cubes	Normal
Configuration of planar stage chuck 2 corner-cubes	Normal
Configuration of the IRPR electronics rack	No IRPR electronics rack present
Constrained fit	Disabled
Continuous clampable wafer table for dry WS	Absent
Control CS_event_check behavior	CS_event_check will block tools if active events exist
Control dose offset per field per wafer	Disable the control of dose offset per field per wafer
Core switch hardware type	No core network switch hardware present
Corr. Per Exposure Lot reporting includes ADELSbcoverlay.	Include the ADELSbcoverlay intrafield contribution.
Correct system drift using semi-active lens elements	Disabled
Correct system drift using semi-active lens elements.	NA
Crosstalk between RSC shape and Z/Ry on product	NA
DEPRECATED Alignment marks segment used during HSA on PARIS	Default
DMCR rack configuration	No DMCR configuration specified
DOSEMAPPER	Present
DOSE_MAPPER_1	Present
DP Storage Backend	Use DDDDB as storage backend
DUV Lightsource Power Level	60.00 Watt
Data Handling Host VP item	Data Handling Host is absent.
Data Trace Manager Toolkit	Motif toolkit
Data collection not covered by FOCUS and OVERLAY	Enabled
Decides if the task queue can contain CPDs or only LOTs	Only allow LOTs to be queued in the task queue
Decides to correct the WSCS-WCS offset	NA
Dedicated Stage Alignment	Disabled
Defines the type of data that is restored	Restore settings and calibration data
Depolarizer type	no retarder but pce-depolarizer
Depth of Focus enhancement with adjustable	Laser bandwidth is not adjustable

laser bandwidth	
Describes at what plane the BMU measures	Correct for BMU below DOE1 level
Determination of NA ellipticity	Disabled
Determines leak detection configuration for the LCW circuit.	No leak detection.
Diaphragm Limiter	Absent
Differentiate between different HIB boards	Three HIB186 boards to determine the positions of the NeXZ
Disable Alignment Laser Configuration	Configuration will not support disabling of alignment lasers
Disable or enable an advanced ESO algorithm	No advanced ESO algorithm is enabled
Disable or enable the encryption of Recipes send to the Tool	Do not encrypt any recipes or layer files on Tool.
Docking wheels at WH unload	Absent
Dose Correction per Pupil Shape	Disabled
Dose Intensity Optimization	NA
Dose System Performance Test for Lithoguide	Present
DoseSystemPerformanceTest sequence	Test sequence 1
Dosecontrol Hardware	DCB
Dynamic Performance Calculation	Mark 3
Dynamic Performance Calculations with Trapezoid slit profile	Enable Trapezoid slit profile
Dynamics Edge Clearance	Dynamics Edge Clearance is supported
E-chuck Flatness Qualification Test	Disabled
EDA Interface	Enabled
EDA Interface standard Freeze	Level I
EDO	Disabled
EFESE	Absent
ENNE Data Collection	Disabled
ER hotlist promotion	Promotion to secs with a generic EXID and ALID
ESCAL execution in wafer production sequence	Not applicable - no ESCAL sensor
ESCAL sensor on chuck 1 present	No ESCAL sensor on chuck 1
ESCAL sensor on chuck 2 present	No ESCAL sensor on chuck 2
ESO Manual Override	ESO Manual Override Disabled
EXE Architecture Revision	None
Editable M-action queues	Editable M-action queues enabled
Electronics-box version of chuck 1	Version 2
Electronics-box version of chuck 2	Version 2
Embedded board diagnostic functionality	Disabled
Enable ExpoFlex functionality	ExpoFlex is available
Enable FIF functionality	FIF functionality is enabled
Enable FIP2 via recipe switch	NA
Enable the Maintenance Assistant	NA
Enable to support SMASH XY mark types.	SMASH XY marks are supported.
Enable/Disable HRG cooling	NA
Enable/Disable Oblique SBO drift for the Alignment Sensor	NA
Enable/Disable SBC2 contribution for SLM	SBC2 contribution not used for SLM calibrate

calibration	
Enable/disable FIWA route stability strategy for 2-opt	FIWA route does NOT use NN-Fix and presort algorithm.
Enabling Dynamic Performance Monitoring improvements	Enable DPM improvements
Energy Sensor	Star TechC
Energy sensor calibration type. Protected	NA
Enhanced Exposure Overlay	Full
Enhanced exposures 1	Present
Enhancements in Reticle Monitor	move feedback inspection overview
Equipment Constants via SECS interface	Enabled
Event Viewer Toolkit	Motif toolkit
Exception Reporting via EDA Interface.	Disabled
Exchangeable Last Lens Element	Present
Exchangeable Pupil Lens Element	Present
Exchangeable Pupil Lens Element Type	EPL Type INACTIVE
Exclude AG to LS offset in AGILE2 AG measurement profile	NA
Extend IRIS maximum particles scanned to 50000.	Present
Extended LS areas	Disabled
Extended Lens Heating History (ELHH)	Enabled
Extended Range Leveling for UVLS	Default
Extended Spot Sensor Matching	Present
Extended Wafer Coverage control	Always on
Extended Zone Alignment	Disabled
Extended maximum for FILS Timeout.	Standard
Extended measurements after expose	NA
Extended minimum for FILS Timeout.	Standard
FIWA Route optimization method	Use 2-opt algorithm on mark distance
FOCAL Measurement for Lithoguide	Present
FSM Flexibility package	Disabled
FSM behavior if Extended Wafer Coverage is enabled for lot	FSM excludes EWC
Fallback type for GLC	No fallback specified for GLC
Field Dependent DOE Exclusion library	NA
Field curvature usage in standalone WBW correction	NA
Field width optimised leveling	Enabled
Filtering of the SUSD correction.	Filtered SUSD correction is disabled.
Fix Encoder drift scan path for NXT3 systems with PEPC	Not applicable
Fix SbO bistable behavior	Coarse capture for HSA of first wafer on the chuck
FlexPol hardware	FlexPol HW is absent
FlexRay Control Rack Configuration	FSCR1
FlexWave Mode for Production	NONE - FlexWave is not used for production
Flexray Fluence Protection 60W	Enabled

Flexray illuminator	Flexray Freeform Mode
Flexwave (2DM) Manifold version	MK1 or MK2
Flexwave exhaust type	Unknown exhaust type
Focus Data Collection	Present
Focus Edge Clearance per Layer	Disabled
Focus Monitoring	Present
Focus Optimizer High Order correction support.	Disabled
Functional use of Active Elements	BALE function as BALE
GOAB firmware with redundant HFmap storage (if applicable).	GOAB firmware with singular HFmap storage (no redundancy).
GPAS sensor type at expose	Not applicable
GPAS sensor type at measure	Not applicable
GPMS reflectivity	Low reflectivity
GWS settings for Imm Hood 6.1 and low gas knife systems.	NA
Gac Algorithm selection for ORION	Default Gac algorithm
Gas Facilities Main Component	GFDU
Gas Facilities: Gas Supply Lens Manipulator	Gas supply lens manipulator hardware not present
Gas Facility / Airknife: Point Of Use Humidifier	NA
Graphical Toolkit for MC/FC/TE Constants Editors	Motif toolkit
Green Laser Attenuation feature	Not Allowed
GridPlate Accelerometer Box	GridPlate Accelerometer Box is absent
GridPlate Active Stiffness damper	Active stiffness units are absent
Gridmapper	Enabled
Hardware configuration identification of balance mass	Balance Mass with 6 DOF Linear Axis
Hardware configuration identification of wafer clamps	Venturi and CF unit MK3
Hardware configuration identification of wafer table clamp	Venturies
Hardware configuration of LoS2BM actuator version	Version 2 (Mk3.0/Mk3.1 actuator)
Hardware configuration of SS actuator of chuck 1	Version 1
Hardware configuration of SS actuator of chuck 2	Version 2
Hardware setting for wafertable BES flow	Wafer table BES at 30 NI/min
Hardware version of Data Handling Host	Absent
Hardware version of Scanner Control Host	x86 mk2.x SSD
High-level measure wafer sequence	Version 2
Higher Order Intrafield Wafer Alignment	Disabled
Horizontal Stage Alignment Capture Strategy	Perform HSA capture
IF Cap Cooling Water Cabinet	IFCWC absent
IH Controlled Parameter Monitoring	Parameter Monitoring is not supported
IH NWE tank pressure sensor	One sensor
ILIAS Functionality For Lithoguide	Present
ILIAS PARIS top-plate bias voltage control mode.	Constant voltage level, using X2 port with optional dongle.

ILIAS Pupil measurement performance node	ILIAS Pupil measurement performance node 19
ILIAS SOMO reticle matching	Disabled
ILIAS Sensor Location	Both
ILIAS X2 Connector Dongle	None
ILIAS Zernike measurement performance node	ILIAS Zernike measurement performance node 19B
ILIAS lens setup	Absent
ILIAS number of supported Zernikes	ILIAS number of supported Zernikes 64
ILIAS sensor type chuck 1	Hyper NA MK5.5
ILIAS sensor type chuck 2	Hyper NA MK5.5
IPMI Reset type for IMCR rack	Reset using master host
IPMI Reset type for MMCR rack	Reset using master host
IRL barcode reader type	1D barcode reader is present at IRL
ISBO measure strategy during Stage Align	Once per Wafer
ISIS Functionality For Lithoguide	Absent
Identification of Positioning Module Supply Box version	Version 2
Identifier planar stage chuck 1 linear axis subversion	Version 0
Identifier planar stage chuck 2 linear axis subversion	Version 0
Illumination Specific Lens Enhancements	Disabled
Illumination modes	All illumination modes
Illuminator Machine Safety Hardware	IDPB
Illuminator Type	NA
Illuminator platform	Aerial XP
Illuminator type	190
Image optimizer generic focus corrections	Disable FOCUS optimizer generic focus corrections
Image quality data path arch	NA
Imaging Control Rack Configuration	IMCR4
Imaging Electronics Architecture	B Architecture
Imaging Fading Control	Lens set-up only
Imaging Generic Power Amplifier	Ten Axis Power Amplifier
Immersion	Present
Immersion CEX version	Version 1 or 2
Immersion Hood Sub version	Sub-Version 1
Immersion Hood SubSub version	Sub-Sub-Version E
Immersion Hood version	Version 5
Immersion hood heater configuration	Four segmented heaters on top
Improved Contrast Control	Absent
Improved Edge Field Leveling	Enabled
Improved FSM algorithm. Part of FIP-1 commercial package.	Enabled
Improved Fallback Leveling activation switch	Deactivates IFL on IFL-enabled machines
Improved Maintenance action scheduling.	Disabled
Improved conditioning in the ILIAS Lens Set Up test	Enabled, perform conditioning at the beginning of the test

Improved wafer reject mode	NA
Improvements for reticle handling	Enabled
In situ Wafer Table Stone Cleaning Hardware Version	NXT: Slow retract unit, microcontroller
In situ Wafer TableStone Cleaning	Present
In situ Wafer TableStone Cleaning Hardware Version	NA
Indication what kind of AM controller hardware is present	DICR
Inlet restriction for clean air	NA
Inline wafer heating correction type	No inline wafer heating control
Insert a delay time before starting a Lot (lens heating).	Disabled
Integrated Reticle Inspection System	NA
Integrated Reticle Inspection System Configuration.	Enable creation of OSIRIS viewable files for PPD2 systems.
Integrated Reticle Inspection System functionality	5um particle detection functionality
Integrated Reticle Inspection System hardware.	IRIS hardware version not configured
Integrated Reticle Library	IRL_XP XCDA PURGED functionality
Intensity Calibration Per DOE	Disabled
Interferometer Electronics	SPMR
Interfield Scan Up Scan Down focus correction	Disabled
Intra-wafer-drift scale factor for TYPE4 reticle control	Use standard Reticle Control scale factor
Intrafield Higher Order Process Correction Mode	15 parameters (no scanning lens parameters) are supported
Intrafield Higher Order Process Corrections	Enabled
Intrafield Higher Order Process Corrections Per Exposure	Intrafield HOPC per exposure is Disabled
Intrafield Higher Order Process Corrections per subfield	Disabled
Intrafield Wafer Alignment	IFWA disabled
Intrafield fingerprint correction.	Functionality is not present.
Iris feature Scan	Present
Is NA accuracy measurement allowed?	Enabled
Is the UPS Ethernet connected to the Twinscan.	UPS is Ethernet connected to the Twinscan.
Is there a Restriction build in the POUH UPW Drain.	No restriction is built in the POUH UPW Drain.
Is this a machine with a safety PLC.	Safety PLC is available in the Twinscan.
Just-in-Time behavior of the wafer handler load robot	Just-in-Time behavior is disabled
LCI WaitWatcher plug-in	Absent
LCW Circuit set-up	Pressure Version 1
LCW leak detection functionality	LCW leak detection functionality for LCW cabinet is disabled
LCWC type for NXT platforms	LCWC-MK4L compatible
LEC Rack in Electronic Architecture	Absent
LS Drift correction strategy	XVSA and IVSA
LS Ry source	XVSA

LS focus node	LS focus node 6
LS spot coverage	Present
LS_PEMM_CONFIG	Absent
LTME Restriction in XCDA DU1	Version 1
LVT modeling version.	LVT model version 1 is enabled.
Laser Gas Life eXtension	Enable Laser Gas Life eXtension;
Laser capability for retrieving High Bandwidth Data	Laser does not provide Bandwidth Data
Layout Independent Leveling	Layout independent wafer leveling is not supported
Layout Version Number TIS Fiducial	Fiducial Layout Version TIS/PARIS
Layout Version Number TIS Plate 1 on Chuck 1	TIS Plate 1 Layout Version 5.5
Layout Version Number TIS Plate 1 on Chuck 2	TIS Plate 1 Layout Version 5.7
Layout Version Number TIS Plate 2 on Chuck 1	TIS Plate 2 Layout Version 5.5
Layout Version Number TIS Plate 2 on Chuck 2	TIS Plate 2 Layout Version 5.7
Layout dependent overlay calibrations	Layout dependent overlay calibrations are disabled
Leave sensor plates with measure marks at a certain speed	Setting 2 : Leave sensor plates at limited speed
Lens Accelerometer Box version	Mark 1
Lens Active Vibration Absorber	Absent
Lens Circuit Water Flow	NA
Lens Control Strategy during lot production	Type 1 Lens state reset for Lot Correction
Lens Heating Feedback	Absent
Lens Heating Package	NA
Lens Model Reticle Stage Mode	Type A
Lens Top Micro Environment Sensors	No Pressure and Temperature sensors
Lens Top Tool Connection	Lens Top Tool can not be mounted on top of the Lens
Lens Type	98
Lens model optimization method	Lens set point calc. based on predefined constraints
Lens move during ESCAL	NA
Lens overpressure compensation during exposure.	Filtered lens overpressure
Level Sensor CPU configuration	Use board If1
Level Sensor DAM version	DAM with initial PDA
Level Sensor Light Source type	Halogen or EQ-99
Level Sensor Processing Rack	MMCR
Level Sensor peripheral configuration	TYPE1 - LM Mk3 or older and DAM NXE or older
Level sensor type	9-spots level sensor
Leveling Field Extensions Algorithm	Use the exposure field averaged values for field extension
Leveling Setpoint Smoothing	Do not use LS spot fading on edge dies
Leveling Verification Test for Lithoguide	Present
Leveling on single LS Spots	Do not use single spot leveling
Leveling with LS Spot Weight Update Algorithm	Selection of LS Spot Weight Update algorithm is not allowed
Levelling throughput improvement on measure side	NA
Light source selection, for FIR laser	NML type Light Source
Light source selection, for NIR laser	NML type Light Source

Light source selection, for green laser	Light source selection 2
Light source selection, for red laser	NML type Light Source
Light-source Architecture	Laser
Light-source Type	Cymer Laser: XLR 660 6.0kHz
Light-source Wave-length	193nm
Lightsource Mark	Mark1
Line of Sight Correction	Line of Sight Correction disabled.
Line of Sight Correction lens accelerometer sensors	Line of Sight Correction sensors absent.
Liquid Particle Counter Unit	NA
Litho InSight Alignment functionality	NA
Lithoguide Imaging Recipes	Absent
Load Robot Internal Docking	NA
Load Robot Wrist Assy Type	NA
Loadport barcode reader type	Original barcode reader at the loadports
Location of PARIS sensor on chuck 1	No PARIS sensor on chuck 1
Location of PARIS sensor on chuck 2	No PARIS sensor on chuck 2
Log missed translations	Disabled
Log total residuals in ADELexposureTrajectoriesReport	Log total residuals
Lot Alignment Report Encryption	NA
Lot Correction Sequence	Type E
Lot Overhead Reduction	LOR2
Lot Report Data Category	Enhanced Diagnostics
MALE used in production.	MALE is enabled in production.
MCH1 hardware version	No MCH1 hardware is present
MDL Viewer	Site View
Machine Architecture	NXT Machine Architecture
Machine Location	Customer Site
Machine Specification	pep-A Specification
Machine Status Lamp	4 Color
Machine Type	1950
Machine focus specification	Focus 1 Specification
Machine imaging specification	Imaging 1 Specification
Machine overlay matching method	BaseLiner MMO style using detrended HF-maps
Machine overlay specification	Overlay 1 Specification
Managed Switch 1 (MSW1) network configuration version	No managed switch 1 is configured in the AERC
Managed Switch 1 type	No MSW1 hardware present
Managed Switch 2 (MSW2) network configuration version	No Managed Switch 2 is configured
Managed Switch 2 type	No MSW2 hardware present
Managed Switch 3 type	No MSW3 hardware present
Managed Switch 4 type	No MSW4 hardware present
Managed Switch 5 type	No MSW5 hardware present
Managed Switch 6 type	No MSW6 hardware present

Matching different reticle groups	Disabled
Max alignment speed	NA
Maximum Reticle ID Length	24 Characters
Maximum numerical aperature (NA) allowed in Lot Production	level 0
Maximum wafer size allowed on the system	Maximum wafer size 300 mm
Measure and model strategy for vertical stage align	NA
Method for alignment of the laser beam	Align beam by optimizing pupil telecentricity params: LUBB
Method to optimize aligned positions	2 color recipes
Metroframe Circuit Water Cabinet	NA
Metroframe Temperature Performance level	NA
Metroframe type	NA
Metrology Focus grid HF correction	Disable the Focus grid HF correction
Metrology focus setup method	Focus setup calibration via CDM3 method
Metrology overlay setup method	BMMO metrology setup
Model switch for MACHINE_OVERLAY_STAB_CTRL = LEVEL_2A	Use old model of LEVEL_2
Modelling for MAXYS	NA
Motor Circuit Water Flow	NA
Move profile parameter configuration chuck 1	Move profile settings 3
Move profile parameter configuration chuck 2	Move profile settings 3
Move to first exposure strategy	First x-move and then y-move or diagonal move
Multi Focal Imaging Mode	Not applicable
Multi Functional Exchangeable Lens Element	Projection lens has no MF-EPL
Multifunction Active Lens Element	2
Multifunctional Active Elements	2
Multilingual UI	Absent
NA Control Architecture	NA3 Half Bridge
NA Control Type	190
NA scaling improvements	NA scaling improvements disabled
NA1 motor type	None
NXE Arch. revision	no revision
NXE Reticle Backside Inspection System	Absent
NXT Arch. revision	revision 1_1
NXT test configuration	No test configuration
NexZ performance mode	Scanning NexZs
Nitrogen purging of Reticle Stage	RS is not purged
Number of Active Elements	
Number of Active Lens Elements	
Number of Active Manipulator Elements	
Number of Bi-directional Active Lens Elements	
Number of EXLE elements	1
Number of Half Dome Mirrors	2
Number of Lens NEXZ Manipulators	6

Number of Lens Z Manipulators Using Camdisk	
Number of RMCS clients	No clients
Number of Rxm	6
Number of Rym	6
Number of Semi-Active X-Y Lens Manipulators	6
Number of Z Lens Manipulators	6
Number of alignment marks at max throughput spec	28 marks
Number of bending points (mirrors).	No mirrors.
Number of manipulable ELLE axes	6
Number of manual overrides for ESO2 and ESO3.	Level 1
Number of pre-amps available per Z-manipulator	
Number of supported fast Zernikes	ILIAS number of supported Zernikes 64
OADB Improved Dynamic Range	Enabled
OIU display hardware	OIU display is implemented by a Sun Ray thin client
ORION sensor version	No ORION version; sensor is not ORION
Obsolete, do not change!	NA
Online Lamp Peak	NA
Operating system of the CT Host	VxWorks
Optimized lens adjustment between WBW and TIS Reticle Align	NA
Option to apply the usage of H0 marks in StageAlign	NA
Overlay Data Collection	Overlay Data Collection enabled.
Overlay Node	Level 0
PARIS HSA measurement strategy	Periodic
PARIS PSM scenario configuration	NA
PARIS Virtual RA Model Version Switch.	NA
PARIS configuration for DCO improvements	NA
PARIS plate shape measurement layout	NA
PARIS rejected pixels report	Disabled
PARIS reticle alignment	PARIS reticle alignment not supported
PARIS sensor performance nodes	PARIS performance node 19A
PCE Location	pce in APEX
PDGC functionality for UVLS	NA
PDOC quality indicator check	PDOC quality indicator functionality is present
PED control mode	Absent
PEP Alignment	No option available
PEP High SLIP	PEP High SLIP is disabled
PEP-ADC Intensity	NA
PGSG REV_ONE setpoint generator improvement	NA
PIPA boardtype	MK2
POB fine setup type	NA
PSE Location	pse in PSER

PSE exchanger functionality	PSE exchanger functionality not available
PSE type	XY polarization
PUPICOM	Absent
PUPICOM Architecture	Multi Spoke
PUPIL Measurement For Lithoguide	Present
PUPILIAS matching in terms of sigma measurement	Match ILIAS MK5 to MK4
PVP constraint to turn on/off reticle cooling functionality	Reticle cooling functionality is not present
PVP for disabling the laser burst interaction functionality	Enabled
Parameter indicates how long overlay data will be stored.	Short retention period.
Patch strategy	Patchlevel
Pattern Matcher	Present
Pattern Matcher Flexray	Freeform subrecipes referencing tuned pupil are not allowed
Pattern Matcher Full Chip	Absent
Pellicle-distortion overlay corrections	No pellicle-distortion corrections
Performance Enhancement Package	None
Physical location of OIU.	OIU is LEFT oriented.
Piezo Active Lens Mounts	Digital MK-2
Point-to-Point LS Machine Matching	Disabled
Polarization	Present
Polarization Shaping Element Retractor	PSER hardware installed in the machine
Polarized illumination amorph DOE.	Only unpolarized illumination.
Position of Spot Sensor on Chuck 1	Spot Sensor Position on Chuck 1 layout 4
Position of Spot Sensor on Chuck 2	Spot Sensor Position on Chuck 2 layout 4
Positioning Module configuration of chuck 1	Normal configuration
Positioning Module configuration of chuck 2	Normal configuration
Possible triggers for disk cleaning	M-action can trigger disk cleaning
Power rack configuration	Phase_1/XTIII electronics (reduced safety settings)
Pre-aligner retry mechanism during continuous rotate	Retry mechanism enabled
Process Dependent Gain Correction	Present
Process Window Optimizer	Version 1
Projection GPA Configuration Version	Version 2
Provides information about number of RS encoders	3 RS encoders
Proximity Matching	Present
Pupil TIS angular sensitivity calibration and correction	TIS Pupil Measurement will not be improved
Pupil forming optics	FlexRay
Pupil measurements with ILIAS	Present
Pupil qualification method	Geometric centre method
QXE Architecture Revision	No revision
QXT Architecture Revision	No revision
RA capture before CEX. Protected.	RA capture in expose sequence always after CEX

RCW1 circuit leak detection	No leak detection
RCW1 leak detection functionality	Leak detection functionality for RCW1 cabinet is disabled.
RCW2 circuit leak detection	No leak detection
RCWC firmware download	Enabled
RCWC mk3 Firmware update	Firmware update enabled
RCWC type	RCWC-Mk2 compatible
REMA architecture	XTREMA
RH Logistics Version Override	RH Logistics is not overridden
RHC fallback method	No fallback
RS Object Field	Shifted 19x0
RS_TORSION_CONTROL PVP	Torsion control disabled
Radial Basis Function Alignment Model	Disabled
Rapid prototyping using Python to control the machine.	Disable rapid prototyping.
ReMa mark	Mark3
Recipe Creator	Absent
Reduce AGILE2 measurement time for UVLS	NA
Reduce Wafer Stage fly-by move disturbance	NA
Reduce focus error for NA changes	NA
Reduce high overlay sensitivities for RS-Rz	NA
Reduce wafer-load-offset tolerance of centring unit to 25 um	Standard
Reduced capture range for TIS scans	NA
Reference Axis Performance Level	Level 1
Relative direction of ws to rs on the X axis	Same
Reorder Lot Service	Present
Report if a Recipe was modified by remote Host or Operator.	Do not report how Recipe was changed.
Reporting of K9/K10 coefficients from reticle alignment	RA_K9_K10_DATA_COLLECTION is Disabled
Reporting of the residuals expected to be seen in resist	Lens finger print, lens model residuals and image tuner
Reporting standard for no-value wafer align data	No-value is not reported
Reset type for VME racks	Serial reset
Reticle Align High Precision	Present
Reticle Balance Mass 1 amp.	550V25A: PAAC XT rev3
Reticle Balance Mass 2 amp.	550V25A: PAAC XT rev3
Reticle Carrier Location	Left
Reticle Carrier Tag Reader	Present
Reticle Exchange Type Version 2	Retex Option: G
Reticle Handler Machine Architecture	Reticle Handler is designed to handle reticles in air.
Reticle Handler type	RH Mark IV
Reticle Heating Control	Reticle Heating Control for NEXZ elements in scanning mode
Reticle Level Polarization Sensor	Present
Reticle Size	6 inch
Reticle Stage Chuck Cleaning Configuration	No valid cleaning configuration

Reticle Stage Chuck Type	TYPE_8: Two part symmetric chuck, wide clamps [Double Entry:] Magn. Grav. Comp. Changed Lens Top
Reticle Stage Lenscooler Box	Lenscooler Box with anti-aliasing Filter
Reticle Stage Long Stroke Config	TYPE_7:moving frame with iron less motor
Reticle Stage Long Stroke Motor Type	Cobalt Ferro 18 teeth
Reticle Stage Long Stroke Y11 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y12 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y13 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y21 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y22 amp.	550V25A: PAAC XT rev3
Reticle Stage Long Stroke Y23 amp.	550V25A: PAAC XT rev3
Reticle Stage Measurement System on Scan	Heidenhain Encoders
Reticle Stage Short Stroke X amp.	PADC 52V/6A
Reticle Stage Short Stroke Y11 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y12 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y21 amp.	PADC 130V/24A
Reticle Stage Short Stroke Y22 amp.	PADC 130V/24A
Reticle Stage Short Stroke Z1 amp.	PADC 52V/6A
Reticle Stage Short Stroke Z2 amp.	PADC 52V/6A
Reticle Stage Short Stroke Z3 amp.	PADC 52V/6A
Reticle Stage Short Stroke Z4 amp.	PADC 52V/6A
Reticle Streaming 3	NA
Reticle Streaming Options	Reticle Streaming 1
Reticle Temperature Sensor	RTS hardware is present
Reticle align capture	NA
Reticle exchange type	Retex option: G
Reticle load protection for too wide/wrongly placed pellicle	Disabled
Reticle shape correction	Enabled
Reticle streaming	NA
Reticle streaming II	NA
Reticle streaming lite	NA
Reuse the ASC corrections based on recipe id and group id	Disables grouping of ASC correction sets
Rotating Stone Wafer Table Cleaning	Disable rotating stone wafer table cleaning
Rough Cooling Water Cabinet 1 (RCWC1) cooling water flow	Full performance flow
Router hardware type	No router hardware present
SAMOS Stray Light Test For Lithoguide	Present
SDM test on machines without SAXY elements	Disabled
SECS Wafer Level Corrections	Not allowed
SMASH 2 color to 4 color support	SMASH 2 color to 4 color upgrade is disabled
SMASH Reuse Capture Information in Stage Alignment	Capture is done and reused per lot.
SPM Dual Speed Data Delay	Present
SPM WS Encoder drift scan	Version 1

SPM Wafer Stage Encoder Measurement System Type	2D Encoders
SPM zeroing plane where zero sensors are configured.	VERSION_0 zeroing plane
SPM_EZCAP_FW_VERSION	SPM_EZCAP_FW_VERSION_2
Save throughput data to the disk	Enabled
Scaling of Lot Correction field effects	Scaling of Lot Correction functionality is absent
Scanning Energy Sensor Calibration	Scanning Energy Sensor Calibration
Select BF3u2 mark positions for Mk5.x PARIS plate	Use non-compliant BF3u2 mark position
Select the version of FOCAL modeling CPD application.	Legacy modeling
Selects wafer correction mode	No wafer corrections
Set PUPICOM use	N_A
Set UNICOM use	N_A
Set setpoint acceleration jerk ratio to constant or variable	Variable
Settle time reduction to improve the throughput	Don't care
Setup sensor board version	Setup SSD version LSDB
Short Chuck-Thermal-Conditioning Post Condition	Setting 1 On BES with BES on
Shot Data Collection	Present
Skip LS spots on TIS gratings for iVSA	Disabled
Skip capture on Horizontal Stage Alignment	NA
Skip capture on horizontal stage alignment (HSA)	Do perform capture during HSA on PARIS plate
Small Alignment Marks Support	No Small Marks
Smart Lens Positioning Function Mode	Smart Lens Positioning functionality is disabled.
Smash increased scan-speed	SMASH increased scan-speeds are disabled
Smash sensor version	SMASH versions up to but not including Mk 3.3
Smooth Field Uniformity	Absent
Software support for the Active Plate Manipulator	Disabled
Specifies chuck1 config	Planar stage Immersion mark 3
Specifies chuck1 version	Version 2
Specifies chuck2 config	Planar stage Immersion mark 3
Specifies chuck2 version	Version 2
Specifies if system is a machine or a test tool	Not applicable
Specifies the Wafer Stage test configuration for WH	No special test configuration
Specifies which mark types are supported	ASML marks and custom marks
Spot Sensor Chuck 1	VLOC
Spot Sensor Chuck 2	VLOC
Spot Sensor Reticle Stage	Present
Spotsensor chuck 1 surface coating	SiO2
Spotsensor chuck 2 surface coating	SiO2
Spotsensor on chuck 1 present	Spotsensor on chuck 1
Spotsensor on chuck 2 present	Spotsensor on chuck 2

Stage Alignment Filter	Absent
Stage Alignment Phases	Fine stage alignment
Stage align just before FIWA	Enabled
Stages Sample Rate	5.0 kHz
Stand-alone Workstation	
Station 1 puck identification	No puck mounted
Station 2 puck identification	No puck mounted
Store Unit bottom pedestal type	Fixed pedestal
Store Unit slot hardware type	Regular Store Unit slots
Strategy for avoidance routing to Pre-CEX park position	Use the shortest route to Pre-CEX park position
Striping correction ILIAS sensor	Enabled
Sub-version of Reticle Stage Long Stroke Configuration	Four Hose Reticle Cooling Configuration
Support chuck specific dose offsets via SECS	Disabled
Support chuck specific focus offsets via SECS	Disabled
Supported FIWA actuation modes	6 Par
Swap bridge 1 type	Swap bridge mark 3.2
Swap bridge 2 type	Swap bridge mark 3.2
Switch INFORMPRO2 Data Package reporting	InformPro2 is unavailable
Switch between default and reduced IH flyheight	NA
Switching stages sample frequency between 10 and 20kHz	10kHz stages servo control
System Startup/Shutdown screen type	Select Motif screen
System drift correction sensor	ILIAS is used for system drift correction
THFFC FDE model lens dependent	Enabled
TIS Advanced Coating Offset Calibration	Disabled
TIS Power switching	Enabled
TIS Reticle Alignment Vert Model Params	Z_Ry
TIS diffuser	TIS diffuser absent
TIS overlay and TPT node	TIS Overlay and Throughput Performance Node 19E
TIS plate deformation correction	Enabled
TIS plate usage in reticle align	NA
TIS plate usage in stage align	SA can skip the TIS1 measurements
TIS trigger mechanism	Use external trigger mechanism
TIS-like PARIS reticle alignment model	NA
TIS_ITOP	Disabled
TOP HD	Present
Test Table	Absent
Test Table Z Axis	Worm Wheel
Test table architecture	Aerial XP
The cpu for 2DM software.	Absent
The type of number cruncher board (NCB)	NA
The version of IADB board	Unspecified IADB version
The version of OADB (Optical Analog Digital converter Board)	OADB Version Mk2

To enable the closing wafer refresh functionality	Enabled
To identify the hw settings and config for Bridge BES flow	This indicates that the SBW_BES underpressure is at -35 kPa
Track Pre-warning signal (APR)	APR enabled
Trajectory Shaping (fading)	Is disabled
Turns on second waferstage host in atca rack	WS2 host is present, and CSGR must try to boot it
Turns on third waferstage host in AMCR rack	WS3 host is present, and CSGR must try to boot it
TwinScan operating altitude after SAT	Low operating altitude
Twinscan GUI display location	Twinscan is displayed at the OIU display
Twinscan autostart	Twinscan autostart is enabled
Type of 1st general purpose amp	TAPA
Type of 5th general purpose amp	TAPA
Type of Air Gauge	TYPE_1: Initial air gauge (-25.5mm)
Type of LS capture	Scanning
Type of MDRC used.	Type number of used MDRC: 2
Type of NEXZ actuator	NEXZ with 885nm range (NO3)
Type of PARIS sensor on chuck 1	No PARIS sensor on chuck 1
Type of PARIS sensor on chuck 2	No PARIS sensor on chuck 2
Type of UV Level Sensor	Visible Level Sensor
Type of filter used in the mirror optics of the UV-LS	No filter
Type of immersion hood for immersion	Actuator Fixed Height
Type of inline cleaning cabinet	NA
Type of preclamp restriction in CF unit/rear PCA of chuck 1	1.0 mm restriction
Type of preclamp restriction in CF unit/rear PCA of chuck 2	1.0 mm restriction
Type of projection multiplexer board	MUX type LAMB
Type of wafertable on chuck 1 for immersion machine	SiSiC version 5.1
Type of wafertable on chuck 2 for immersion machine	SiSiC version 5.1
UNICOM	Present
UNICOM Architecture	58 Motors
UPWC Mark 1 Process Cooling Water (PCW) valve setting	NA
UV Shutter version	NA
UV level sensor spot correction	NA
Ultra Pure Water Cabinet (UPWC) version	UPWC Mark 2
Unicom gray filter configuration	gray filter configuration has a slot for only one filter
Unicom gray filter mode	Single gray filter mode
Unicom move check	Unicom move check enabled
Uniformity Improvement Package	Present
Universal Prealignment	Disabled
Unload Robot Wrist Assy Type	NA
Usage of Energy Sensor data by TIS	Enabled
Usage of wavelength data by TIS	Enabled

Use Sigma Calibration	no Sigma Calibration
Use Sigma WIP Preserving Offsets	no Sigma WIP Preserving Offsets
Use global wafer shape instead of wedge in fallback fields	Disabled
Use of 12COLOR in alignment reporting	Reporting disabled
Use validity ranges around UIP data when Enabled.	Use exact matching for UIP data
Version of the Air Control Cabinet (ACC)	ACC MK 1 to 4
Version of the Dual HSSL PCI card on the ZK SCCB	Version 1
Visibility and editability of ESO3 table machine constants	Disable visibility and editability
WH Dock spring leaf cam typ	Hard
WH Load Robot gripperpad type	Normal gripperpad
WH Robot Power Amplifier	CPM 20
WH Unload Robot gripperpad type	Normal gripperpad
WH temperature conditioning type	Fast performance type used for XTIV and higher.
WS dynamic full data report	Disabled
WS encoder plate suspension	WS encoder plates are suspended on vibration dampers
Wafer Alignment Model Mapping	Disabled
Wafer Alignment modeling modes	Only one wafer alignment model per model step
Wafer Carrier Location	Left
Wafer Handler Ambient Release throughput optimization	Disabled
Wafer Handler Brake Box Type identification	No Brake Box installed
Wafer Handler Manifold Heater	Usage of the manifold heater is prohibited
Wafer Handler Pre-aligner Type	Pre-aligner with air-bearing table
Wafer Handler Productivity	Wafer Handler Productivity Level 0
Wafer Handler Store Unit Bottom Table Type identification	No Table installed
Wafer Handler improved robot takeover positioning	Disabled
Wafer Handler motion architecture configuration	PID/GIOS Based motion control
Wafer Handler wrt BF Shifted in Z	NA
Wafer Handling Docking Plate	WH Docking Plate Docking Body
Wafer Handling Drying Unit	WH Drying Unit Present
Wafer Handling Load Robot Type	Scara Arm, 50 mm Z stroke
Wafer Handling Pneumatics	Standard
Wafer Handling Store Unit Type	WH Store Unit 4 Slotted
Wafer Handling TSU	WH TSU Heater Present Inactive
Wafer Handling Test configuration	No test configuration (real)
Wafer Handling Track Input	WH Wafer Track Input Via SU
Wafer Handling Unload Robot Type	Scara Arm, 50 mm Z stroke
Wafer Id Reader	NA
Wafer Level Overlay Corrections	Wafer level correction is disabled
Wafer Load Grid settings	Baseline
Wafer Load settings	NA

Wafer Mark Sensor	Absent
Wafer Size	300mm
Wafer Stage Configuration	Wafer Stage type 1 configuration
Wafer Stage Dynamic Disturbance Reduction	Disabled
Wafer Stage Expose Move Strategy	Version 1
Wafer Stage Exposure Defectivity Routing	Disabled
Wafer Stage Measurement System	Heidenhain encoders
Wafer Stage Type	Dual Chuck
Wafer Stage WEX TPT	Default WEX TPT
Wafer Stage WEX method.	Default WEX method
Wafer Stage measure to expose/expose to measure feed forward	Disabled
Wafer Stage to Airmounts feed forward functionality	Disabled
Wafer Switch	NA
Wafer Table Heater Control	Disabled
Wafer Table Reconditioning	Absent
Wafer Table unflatness overlay drift correction	Disabled
Wafer Track	Present
Wafer Unload settings	Wafer Unload sequence 3
Wafer Z-Map modeling algorithm	Wafer Z-Map modeling algorithm: Discrete
Wafer alignment layout import modes	Layout import not allowed
Wafer approval strategy	Standard wafer approval
Wafer path from Carrier	Directly to pre-aligner
Wafer positioning SIOB configuration	SIOB-5 installed
Wafer stage power cabinet electronics	Config 4
Wafer stage technology	Wafer stage planar drive
Wafer type used in the machine	300 mm - SEMI Notch
Wafer unload type	Wafer unload under baseframe control
Wafer warpage measurement hardware type	No wafer warpage measurement hardware installed
Wafer z-map type.	Type 2: On-the-fly setpoints - no GLC
WaferTable BES sensitivity setting	Level 1 Default
Wafers per Carrier	25
Warped wafer shape support	Disabled
Wavelength Adjustable	Adjustable
Wavelength range of the light source	DUV wavelength family: 248nm or 193nm
Wet Chuck Ex. while stay hovering (Chuck1=Exp,Chuck2=Mea)	Hovering is enabled during CEX
Wet Chuck Ex. while stay hovering (Chuck1=Mea,Chuck2=Exp)	Hovering is enabled during CEX
Wet Vacuum unit version in EIM	Type B WVAC EIM unit installed
Whether or not to perform self-lock	Self-lock must not be performed
Wide Pellicle Detection	Present
Wide Pellicle Detection Type	OPTICAL
X-Matching Generation	Machine Generation level 0
XCHA Distribution Unit Version	MK1 or MK2

XML Lot Report Content Level	Extended
XML output for LITHOGUIDE	Disabled
XT Architecture Revision	None
XT REMA MPAC board type	MPAC type 2
XVSA Spot Selection and Modeling Correction	NA
Z-capture on low reflectivity wafers	Z-capture on low reflectivity wafers is disabled.
ZERO Fiducial	ILIAS MK4
Zmap scan profile type for Wafer Zmap	Wafer Z-map using constant velocity scan profiles
Zoom Axicon Architecture	ZZA
Zoom Axicon Type	190
board configuration	OADB
dHDM optimization mode in lens models.	No dHDM actuation
eiHOPC range extension	Extended iHOPC range extension is disabled
extended docking interface at Prealigner	ECC_0MM
for ASML created PDOC and PDGC subrecipes deletion	Prevent deletion of ASML created PDGC and PDOC subrecipes
iHOPC corrections per exposure per wafer	iHOPC per exposure per wafer is not allowed
iHOPC corrections per image per wafer	iHOPC per image per wafer is not allowed
iHOPC per image per chuck	Is not allowed
iHOPC range extension K7, K12 and K13	IHOPC Ranges extension K7, K12 and K13 is enabled
iVSA subsampling for PARIS plate degradation	Use all measured spots for modeling
mbds control	Present
routing for ASML test purposes	Disabled
switch for 3DOF / 6DOF HDM	NA
switch for 3DOF HDM / 6DOF HDM / sHDM / dHDM	HDM_TYPE_6DOF
wildcard matching to use reticle heating TOPRC records	Reticle heating control calibration record reuse is mode0
xCWC firmware download	Enabled